

**CERTIFICATE OF COMPLIANCE – RoHS Compliance Declaration**  
(in accordance with ISO/IEC 17050-1:2004)



**Integrated Device Technology Inc.**  
**6024 Silver Creek Valley Road,**  
**San Jose, CA 95138.**

This is to certify that All IDT Flip Chip products meet the requirements of the **RoHS Directive 2002/95/EC** issued January 27, 2003 with the following exemption listed in the Annex of the RoHS directive

**15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.**

The following table lists the restricted materials and their respective allowable limits:


<b>RoHS Restricted Substance</b>	<b>Allowable Limit</b>
Cadmium and its compounds*	100 ppm (0.01 weight %)
Mercury and its compounds	1000 ppm (0.1 weight %)
Hexavalent chromium and its compounds	1000 ppm (0.1 weight %)
Lead and its compounds**	1000 ppm (0.1 weight %)
Polybrominated biphenyls (PBB)	1000 ppm (0.1 weight %)
Polybrominated diphenyl ethers (PBDE) (including DecaBDE)	1000 ppm (0.1 weight %)

**\*note the allowable limit for Cadmium is 100 ppm (0.01 wt.%)**

**\*\*exemption for high lead in the internal package interconnect (Flip Chip packages)**

This information concerning the substances contained in product is based on the information provided by third parties. IDT does not routinely conduct destructive testing or chemical analysis of incoming material and does not warranty and guarantee the accuracy of the information. IDT does, however, possess a reasonable belief that the information herein is representative and accurate.

This declaration pertains to the finished product and does not include packing materials such as IC trays, plastic bands, plastic tubes, cardboard boxes, etc.

Name: LS Koay  
Signature/Date:  July 01 /2008  
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